### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT6269701

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Wen-Hsin Lin	08/12/2020
Shin-Chen Lin	08/12/2020
Yu-Hao Ho	08/12/2020
Cheng-Tsung Wu	08/12/2020
Chiu-Hao Chen	08/12/2020

#### **RECEIVING PARTY DATA**

Name:	Vanguard International Semiconductor Corporation	
Street Address:	123, Park Ave-3rd, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17003946

### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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**Correspondent Name:** WINSTON HSU

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Address Line 4: **NEW TAIPEI CITY, TAIWAN** 

ATTORNEY DOCKET NUMBER:	VISP0042USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	08/26/2020

**Total Attachments: 10** source=3937952#page1.tif source=3937952#page2.tif source=3937952#page3.tif

> **PATENT** REEL: 053608 FRAME: 0397 506222958

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PATENT REEL: 053608 FRAME: 0398

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

#### Title of Invention:

## HIGH-VOLTAGE SEMICONDUCTOR DEVICE AND METHOD OF FORMING THE SAME

As the below named inventor, I here this declaration is directed to:	by declare that:	-		
☑ The attached application, or	•			
□ United States application nu	mber	filed on, or		
☐ PCT international application	number	filed on	_	
The above-identified application was	made or authorized to be made I	py me.		
I believe that I am the original invente application.	or or an original joint inventor of a	claimed invention in the		
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this decisonment of not more than five (5)	laration is punishable years, or both.		
In consideration of the payment by	Vanguard International Semiconductor Corporatio	having a postal address	s of	
123, Park Ave-3rd, Hsinchu S	cience Park, Hsinchu 30077	, Taiwan, R.O.C.		
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		0), the receipt of which is hereby	<b>/</b>	
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements witton and, in and to, all Letters Pate any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals,		
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention and said L cessary or desirable to carry out t	etters Patent and said he proposes thereof.	•	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

Page 1 of 10

NPO#VIS-P0042-USA:0 CUST#108024

LEGAL NAM	ME OF INVENTOR	(ASSIGNOR)		
Inventor:	Wen-Hsin Lin		Date:	2020, 8, 12
Signature:	Wen-Hsin	Lin		

Page 2 of 10

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☑ The attached application, or		
United States application number	filed on	, or
☐ PCT international application number	filed on	
The above-identified application was made or authorized to	be made by me.	
I believe that I am the original inventor or an original joint in application.	ventor of a claimed invention in	n the
I hereby acknowledge that any willful false statement made under18 U.S.C. 1001 by fine or imprisonment of not more the		le
In consideration of the payment by Vanguard Internat Semiconductor Co		ostal address of
123, Park Ave-3rd, Hsinchu Science Park, Hsinc	hu 30077, Taiwan, R.O.C	•
(referred to as "ASSIGNEE"below) to I of the sum of One D acknowledged, andfor other good and valuable consideration		ich is hereby
I hereby sell, assign and transfer to ASSIGNEE and the suc the entire right, title and interest in and to any and all impro- invention as above-identified application and, in and to, all l invention by the above application or any continuations, con substitutes, or extensions thereof, and as to Letters Patent	vements which are disclosed in Letters Patent to be obtained for ntinuation-in-part, divisions, rer	n the or said newals,
I hereby covenant that no assignment, sale, agreement or entered into which would conflict with this assignment;	encumbrance has been or will l	be made or
I further covenant that ASSIGNEE will, upon its request, be and documents relating to said invention and said Letters P known and accessible to I and will testify as to the same in related thereto and will promptly execute and deliver to ASS	atent and legal equivalents as any interference, litigation prod	may be
representatives any and all papers, instruments or affidavits maintain, issue and enforce said application, said invention equivalents thereof which may be necessary or desirable to IN WITNESS WHEREOF, I have hereunto set hand and se	and said Letters Patent and sa carry out the proposes thereo	f.
Note: An application data sheet (PTO/SB/14 or equivalent), inventive entity, must accompany this form. Use this form fo		

Page 3 of 10

NPO#VIS-P0042-USA:0 CUST#108024

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Shin-Chen Lin

Date: >020. 8-12

Signature:

Page

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### Title of Invention:

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☐ United States application nu	mber	filed o	n	, or
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The above-identified application was	made or authorized to be	made by me.		
I believe that I am the original inventor application.	or or an original joint inver	ntor of a claime	d invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri				
In consideration of the payment by	Vanguard Internation Semiconductor Corp		having a postal add	ress of
123, Park Ave-3rd, Hsinchu So	cience Park, Hsinchu	30077, Taiw	an, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dolla d valuable consideration.	ar (\$ 1.00), the	receipt of which is he	reby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and	nd to any and all improven tion and, in and to, all Lett any continuations, contin	nents which are ers Patent to b uation-in-part,	e disclosed in the e obtained for said divisions, renewals,	EE
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	lication, said invention an cessary or desirable to ca	d said Letters F arry out the prop	Patent and said poses thereof,	•
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#VIS-P0042-USA:0 CUST#108024

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yu-Hao Ho Date:

>020.08.12

Yu- Hao

Page

F#NPO-P0002E-US1201

### COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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☑ The attached application, o	r		
☐ United States application n	umber	filed on _	, or
☐ PCT international application	on number	filed or	· ·
The above-identified application wa	as made or authorized to	be made by me.	
I believe that I am the original inver application.	ntor or an original joint inv	entor of a claimed inv	ention in the
I hereby acknowledge that any willf under18 U.S.C. 1001 by fine or imp			
In consideration of the payment by	Vanguard Internati Semiconductor Co		ving a postal address of
123, Park Ave-3rd, Hsinchu	Science Park, Hsincl	nu <b>30077</b> , Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) acknowledged, andfor other good a			pt of which is hereby
I hereby sell, assign and transfer to the entire right, title and interest in invention as above-identified applic invention by the above application substitutes, or extensions thereof, a	and to any and all improv cation and, in and to, all L or any continuations, con	ements which are disc etters Patent to be ob tinuation-in-part, divis	closed in the tained for said ions, renewals,
I hereby covenant that no assignmentered into which would conflict w		ncumbrance has beer	ı or will be made or
I further covenant that ASSIGNEE and documents relating to said inveknown and accessible to I and will related thereto and will promptly ex	ention and said Letters Pa testify as to the same in a	atent and legal equiva any interference, litigal	lents as may be
representatives any and all papers, maintain, issue and enforce said ar equivalents thereof which may be r IN WITNESS WHEREOF, I have he	oplication, said invention a necessary or desirable to	and said Letters Pater carry out the propose	nt and said s thereof.
Note: An application data sheet (PT inventive entity, must accompany to			

Page 7 of 10

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Cheng-Tsung Wu	Date:	20,8,020	
Signature:	Cheng-Tsung Wm	, , , , , , , , , , , , , , , , , , , ,		

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# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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The above-identified application was made or authorized to be made by me.			
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
In consideration of the payment by	Vanguard International Semiconductor Corporation	having a postal addre	ess of
123, Park Ave-3rd, Hsinchu Science Park, Hsinchu 30077, Taiwan, R.O.C.			
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.			
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.			
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;			
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.			
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.			

Page 9 of 10

DSB0-109U029504

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chiu-Hao Chen

Date: 08/12/2020

Signature: Chiu - Hao Cheh Ph. Ph. Cheh

NPO#VIS-P0042-USA:0 CUST#108024

**RECORDED: 08/26/2020** 

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